

Features

- Glass passivated chip junctions
- Ideal for automated placement
- Ultrafast reverse recovery time for high efficiency
- Low profile package
- High forward surge capability
- High temperature soldering: 260°C/10 seconds at terminals
- Component in accordance to RoHS 2002/95/1 and WEEE 2002/96/EC



SMB (DO - 214AA)

Mechanical Data

- **Case:** JEDEC DO-214AA molded plastic body over glass passivated chip
- **Terminals:** Solder plated, solderable per JESD22-B102
- **Polarity:** Laser band denotes cathode end

Major Ratings and Characteristics

$I_{F(AV)}$	2.0 A
V_{RRM}	50 V to 600 V
I_{FSM}	50 A
t_{rr}	35 nS
V_F	0.95 V, 1.25 V, 1.7 V
$T_j \text{ max.}$	150 °C

Maximum Ratings & Thermal Characteristics

($T_A = 25\text{ °C}$ unless otherwise noted)

Items	Symbol	ES2A	ES2B	ES2C	ES2D	ES2E	ES2G	ES2J	UNIT
Maximum repetitive peak reverse voltage	V_{RRM}	50	100	150	200	300	400	600	V
Maximum RMS voltage	V_{RMS}	35	70	105	140	210	280	420	V
Maximum DC blocking voltage	V_{DC}	50	100	150	200	300	400	600	V
Maximum average forward rectified current	$I_{F(AV)}$	2							A
Peak forward surge current 8.3 ms single half sine-wave superimposed on rated load	I_{FSM}	50							A
Thermal resistance from junction to lead ⁽¹⁾	$R_{\theta JL}$	25							°C/W
Operating junction and storage temperature range	T_J, T_{STG}	-55 to +150							°C

Note 1: Mounted on P.C.B. with 0.28 x 0.28" (7.0 x 7.0mm) copper pad areas.

Electrical Characteristics ($T_A = 25\text{ °C}$ unless otherwise noted)

Items	Test conditions		Symbol	ES2A~D	ES2E~G	ES2J	UNIT
Maximum Instantaneous forward voltage	$I_F=2A^{(2)}$		V_F	0.95	1.25	1.70	V
Maximum reverse current	$V_R=V_{DC}$	$T_j=25^{\circ}C$	I_R	5			μA
		$T_j=125^{\circ}C$		50			
Reverse recovery time	$I_F=0.5A$ $I_R=1A$ $I_{rr}=0.25A$		t_{rr}	35			nS
Typical junction capacitance	4.0 V ,1MHz		C_J	18			pF

Note 2: Pulse test: 300μs pulse width, 1% duty cycle.

Characteristic Curves (T_A=25 °C unless otherwise noted)

Fig.1 Forward Current Derating Curve

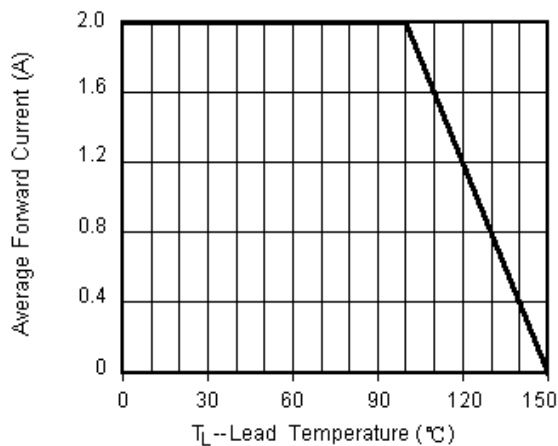


Fig.2 Maximum Non-Repetitive Peak Forward Surge Current

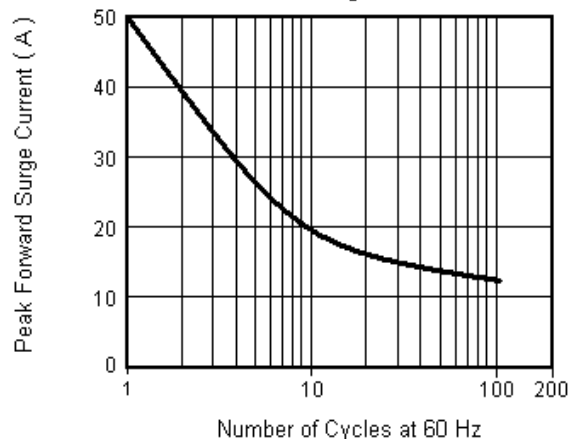


Fig.3 Typical Instantaneous Forward Characteristics

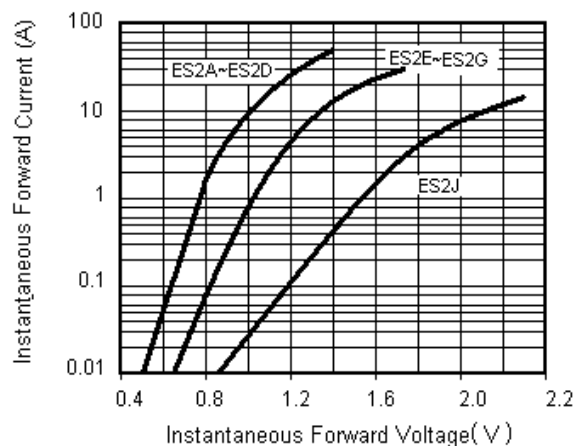
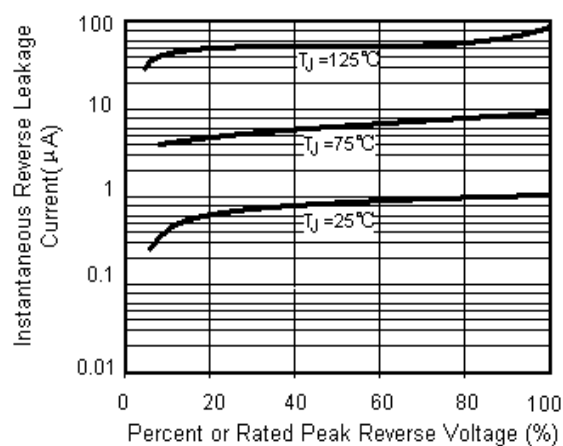
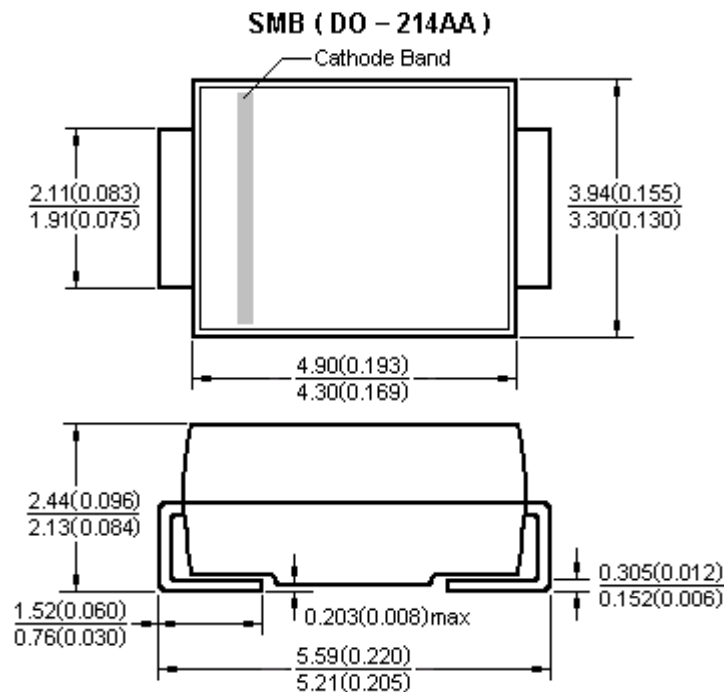


Fig.4 Typical Reverse Leakage Characteristics



Package Outline



Dimensions in millimeters and (inches)

Notice

- Product is intended for use in general electronics applications.
- Product should be worked less than the ratings; if exceeded, may cause permanent damage. or introduce latent failure mechanisms.
- The absolute maximum ratings are rated values and must not be exceeded during operation. The following are the general derating methods you design a circuit with a device.
 $I_{F(AV)}$: We recommend that the worst case current be no greater than 80% .
 T_J : Derate this rating when using a device in order to ensure high reliability. We recommend that the device be used at a T_J of below 125°C.

- TRR is registered trademark of Zhejiang TRR Microelectronics Inc.. Zhejiang TRR Microelectronics Inc. reserves the right to make changes to any product in this specification without notice.
- Zhejiang TRR Microelectronics Inc. does not assure any liability arising out of the applications or use of any product described in this specification.
- Zhejiang TRR Microelectronics Inc. advises customers to obtain the latest version of the device information before placing orders to verify that the required information is current.